

## 30V<sub>DS</sub>/±20V<sub>GS</sub> N-Channel Enhancement Mode MOSFET

### Features

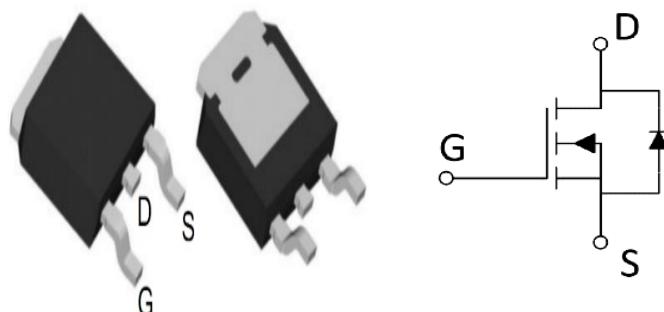
- Reliable and Rugged
- Avalanche Rated
- Low On-Resistance
- High Current Capability

BVDSS	RDS(ON)	ID
30V	10mΩ	50A

TO-252

### Applications

- Load Switch
- Power management in portable/desktop PCs
- DC/DC conversion



### Ordering Information

Device	package	Device Marking	Package Qty.
JMTK50N03A	TO-252	TK50N03A	2500/PCS

### Absolute Maximum Ratings (T<sub>C</sub>=25°C,unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	V <sub>DS</sub>	30	V
Gate-Source Voltage (V <sub>GS</sub> =0V,static)	V <sub>GS</sub>	±20	V
Continuous Drain Current (T <sub>C</sub> =25°C)	I <sub>D</sub>	50	A
Continuous Drain Current (T <sub>C</sub> =100°C)		33	A
Pulses Drain Current	I <sub>DM</sub>	115	A
Maximum Power Dissipation	P <sub>D</sub>	37	W
Single pulse avalanche energy	E <sub>AS</sub>	24	mJ
Operating,Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55~175	°C

### Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance,Junction-to-Case	R <sub>θJC</sub>	-	2.5	-	°C/W

## Electrical Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$	-	-	1	$\mu A$
Gate -Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.6	3	V
Drain-SourceOn-stageResistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	7.5	10	$m\Omega$
		$V_{GS}=4.5V, I_D=20A$	-	11	17	

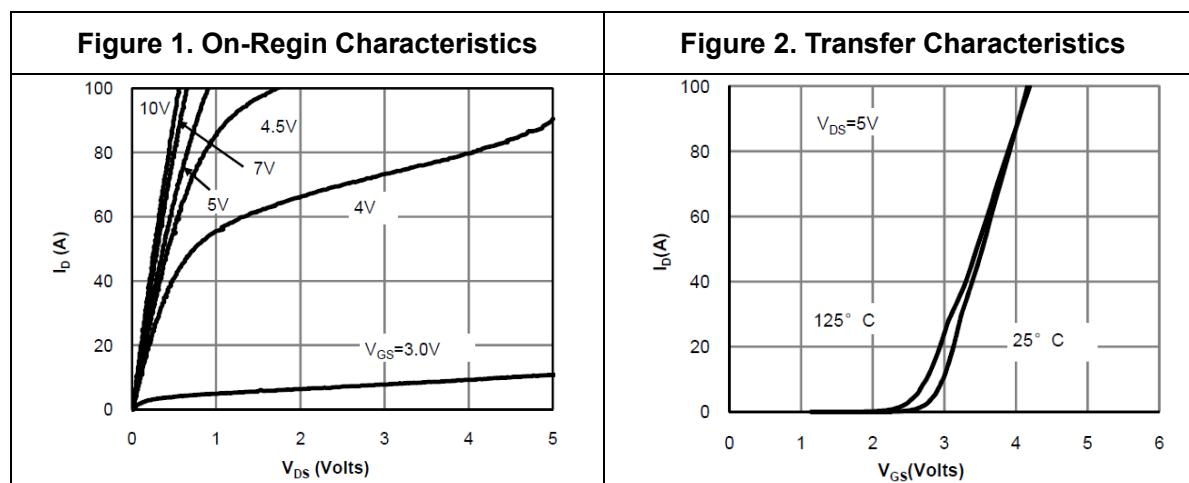
## Dynamic Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input capacitance	$C_{iss}$	$V_{DS}=15V$ $V_{GS}=0V$ $f=1MHz$	-	940	-	pF
Output capacitance	$C_{oss}$		-	131	-	
Reverse transfer capacitance	$C_{rss}$		-	109	-	
Gate Resistance	$R_g$	$f=1MHz$	-	1.5	-	$\Omega$
Total Gate Charge	$Q_g$		-	70	-	nC
Gate Source Charge	$Q_{gs}$		-	4.8	-	
Gate Drain Charge	$Q_{gd}$	$I_D=20A$	-	16.3	-	
Turn-on delay Time	$t_{d(on)}$	$V_{GS}=10V$ $V_{DS}=15V$ $R_L=0.75\Omega$ $R_G=3\Omega$	-	11	-	ns
Rise time	$t_r$		-	16	-	
Turn-off delay Time	$t_{d(off)}$		-	42	-	
Fall time	$t_f$		-	16	-	

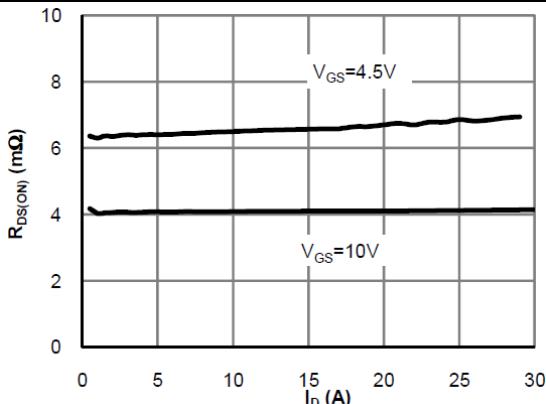
## Reverse Diode Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Body Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=1A$	-	0.85	1.2	V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_{SD}=20A$	-	22	-	ns
Reverse Recovery Charge	$Q_{rr}$	$d_i/d_t=500A/\mu s$	-	11	-	nC

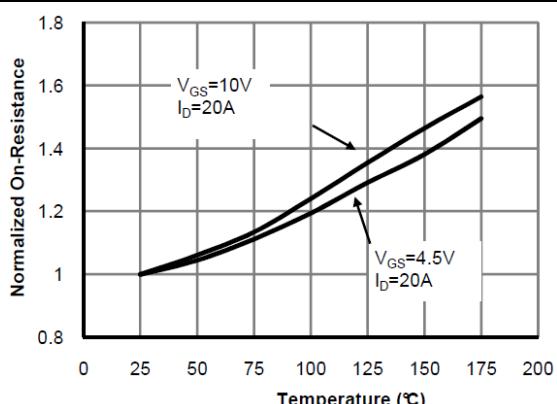
## Electrical Characteristics Diagrams



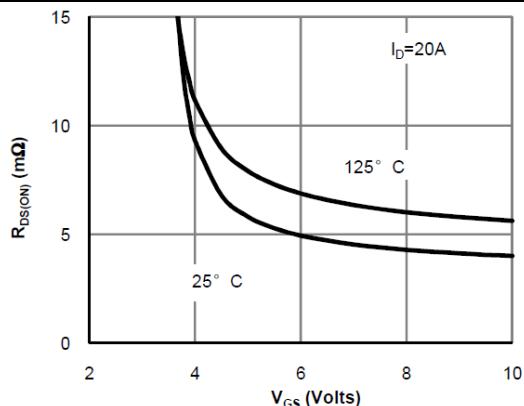
**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**



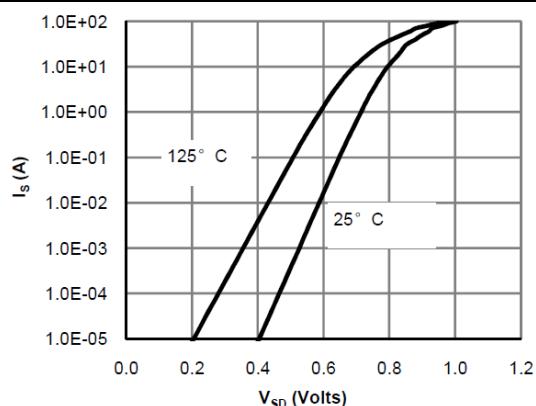
**Figure 4. On-Resistance vs. Junction Temperature**



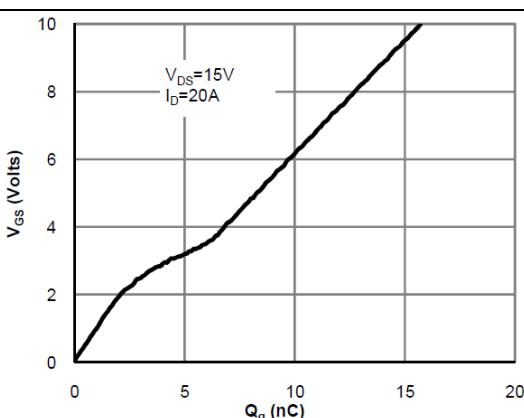
**Figure 5. On-Resistance vs. Gate-Source Voltage**



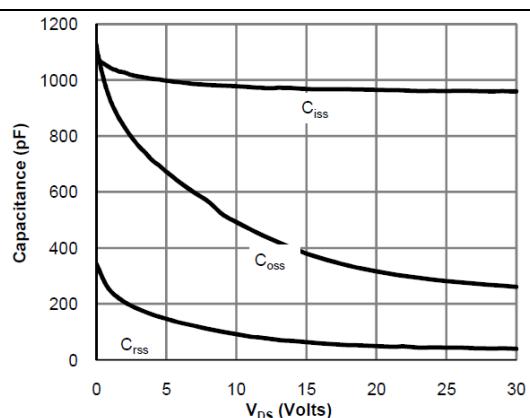
**Figure 6. Body-Diode Characteristics**



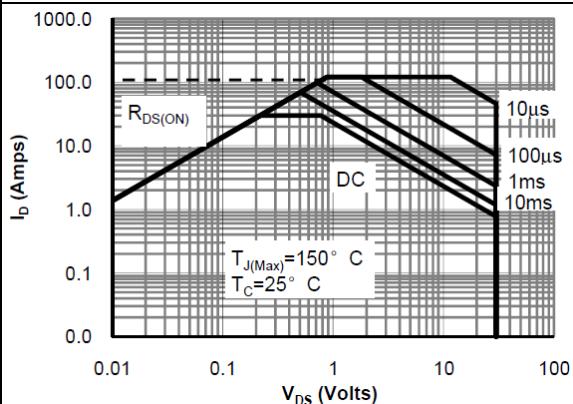
**Figure 7. Gate-Charge Characteristics**



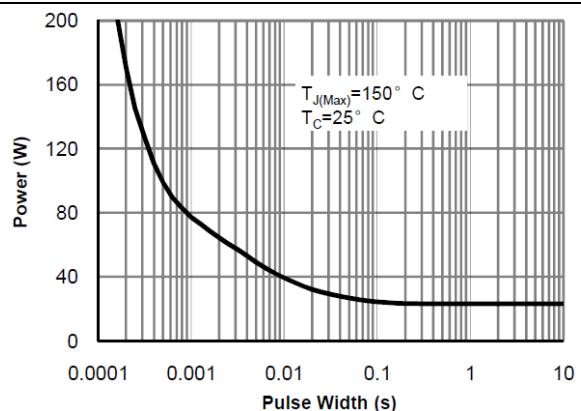
**Figure 8. Capacitance Characteristics**



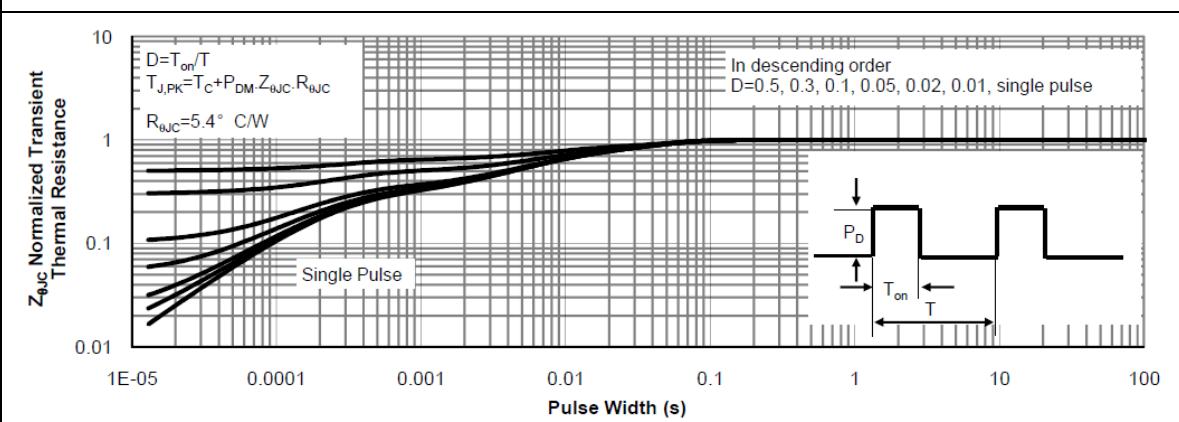
**Figure 9. Maximum Forward Biased Safe Operating Area**



**Figure 10. Single Pulse Power Rating Junction-to-Case**



**Figure 11. Normalized Maximum Transient Thermal Impedance**



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